An Integrated Circuit for Feedback Control & Compensation of an Organic LED Display

by

Kartik **S.** Lamba

Submitted to the Department of Electrical Engineering and Computer Science

in partial fulfillment of the requirements for the degree of

Master of Engineering in Electrical Engineering and Computer Science

at the

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in whole or in part. **MASSACHUSETTS INSTITUTE OF TECHNOLOGY AUG 1 4 2006 LIBRARIES** Author **. , .** Oe~rtent of Electrica ngineering and Computer Science February 21, 2006 **Certified by** Charles **G.** Sodini Professor *.4* Thesis Supervisor **.......** Certified **by** .Vladimir Bulovic Associate Professor esis Supervisor Accepted **by** cacific **.** Arthur **C.** Smith Chairman, Department Committee on Graduate Students

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Abstract

Organic LEDs (OLEDs) have the potential to be used to build large-format, thin, flexible displays. Currently, the primary drawback to their usage lies in the difficulty of producing OLEDs which emit light at a constant and predictable brightness over their lifetime. **A** solution has been proposed which uses organic photo-detectors and optical feedback to control the desired luminosity on a per-pixel basis. This thesis demonstrates the design and fabrication of an integrated silicon control chip and an organic pixel/imaging array, which together form a stable, usable display. The simulation, verification, and testing of this **OLED** display demonstrates the utility of our solution. In particular, this thesis focuses on the Loop Compensator silicon design and feedback aspects of this circuit. The results demonstrate that the Loop Compensator has the desired **DC** and frequency characteristics with a measured gain of 100.2 and a variable dominant pole located at digitally-selectable frequencies (using a programmable capacitor array) of **10.8** Hz, **13.5** Hz, **22.8** Hz, and 64.8 Hz, given a clock frequency of 20 kHz.

Thesis Supervisor: Charles **G.** Sodini Title: Professor

Thesis Supervisor: Vladimir Bulovic Title: Associate Professor

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Chapter 1

Introduction

An essential part of modern electronics is the display. It is one of the most intuitive and user-friendly methods of communicating information. Large-format displays are particularly useful when there is a copious amount of data, or when the intended audience is distributed over a sizable zone. The telecommunications industry, for example, uses large-format displays to visualize massive amounts of data at full scale in order to monitor their networks and services. Modern sports venues are increasingly using larger displays to convey interactive game information and advertisements from their sponsors. Even highway billboards have evolved from static signs to dynamic, animated displays. High-resolution, large-format displays are crucial in presenting this information properly [1].

Unfortunately, current electronic display technologies cannot easily be scaled to these large dimensions. Current solutions typically involve tiling many displays together to form a wall of images. While graphics hardware exists to support these kinds of visualizations, the displays themselves are not flexible, power-efficient, or portable. The most prevalent display technology is the Liquid Crystal Display **(LCD).** As a mature technology, however, LCDs have many limitations which can greatly influence the overall system design. These drawbacks include power inefficiency, size limitations, and the physical inflexibility of the display.

An Organic Light Emitting Diode **(OLED)** display is a technology in its relative infancy, but offers a promising solution for large-format, low-power, inexpensive displays. However, the voltage-to-light characteristics of OLEDs are still difficult to match from device-to-device, and can degrade significantly over time. This disadvantage severely limits the display functionality and lifetime **(~1000** hours) [2].

1.1 Thesis Objectives & Motivation

This thesis aims to remedy the primary disadvantage of **OLED** displays (degradation and variation) described above. Through the use of organic photo-detectors (OPDs) and optical feedback control, this novel **OLED** display design will overcome nonuniformities, variations in **OLED** voltage-current characteristics among devices, and degradation over time. This feedback will allow for more consistent and better display performance under a wide variety of conditions and environments, as well as extend the display lifetime substantially.

1.2 Thesis Organization

This thesis is organized in the following manner. Chapter 2 provides a background of current display technologies. Particularly, it describes the advantages and disadvantages of both **LCD** and **OLED** displays. It also includes some of the prior work conducted at MIT in this field. Chapter **3** covers the design of the organic portion of the system. This includes both the **OLED** pixel as well as the OPD sensor. Chapter 4 presents the **OLED** optical feedback solution which is the focus of this thesis. It describes its overall implementation and partitions the design into smaller blocks. Chapter **5** discusses the design of the silicon part of the system. Particularly, it describes the design and implementation of the loop compensator, which is the primary focus of this thesis. Chapter **6** details the full integrated silicon chip designed and fabricated for this thesis, describes the testing procedure, and discusses measured results. Chapter **7** concludes the thesis **by** providing a broader context for the results and proposing potential future work.

Chapter 2

Background

2.1 Liquid Crystal Display Overview

LCDs use polarizers and liquid crystals to effectively create a light filter. When an electric field is applied across the crystal, the liquid crystal can rotate the optical axis of incident light. Together with the two plane polarizers, one in front and one in back, the layers create an analog switch for each color at each pixel. Thus, liquid crystals themselves are non-emissive and require a bright backlight to function as a display. This poses several limitations on **LCD** technology.

LCDs are not very power efficient compared to **OLED** displays. In a **LCD,** a backlight is required to illuminate the pixels. After passing through the two plane polarizers, liquid crystal layer, and TFT layer (thin film transistor), as little as **5%** of the incident light will reach the user **[3].** Thus, LCDs have extremely low efficiency **(-1** lm/W) compared to that of OLEDs **(5** lm/W for blue, **600** lm/W for green, and **15** lm/W for red) [4]. Large-format LCDs may not be feasible due to their large power consumption, whereas **OLED** displays should not suffer from such a problem **[5].**

2.2 OLED Display Overview

2.2.1 OLED Display Advantages

OLED displays present a solution to all of the issues raised above and offer an exciting alternative to LCDs. As a direct emission technology, **OLED** displays are not only much more power efficient than LCDs, but they also don't suffer from viewing-angle limitations. Additionally, the scalability of OLEDs make it much easier to create large displays several meters in size.

Other advantages of **OLED** displays include flexibility and cost efficiency. OLEDs are inherently thinner devices $(\sim)1$ micron in thickness) than LCDs and can be fabricated on thin substrates such as plastic, permitting curved and flexible displays. In addition, OLEDs and organic transistors can be fabricated using processes much simpler and cheaper than silicon processes, and typically at room temperature. Thus, an all-organic **OLED** display can be easily scaled for large-area displays, such as posters or billboards **[6].**

Research on organic optoelectronics over the past two decades has advanced OLEDs significantly to render them suitable for a display technology. Power efficiencies have increased from **0.1-1** lm/W to **10-100** lm/W. And new topologies, techniques, and organics have allowed OLEDs to become much more stable. Already, there are a few corporations that have begun to commercialize **OLED** display technology **[7].**

2.2.2 OLED Display Disadvantages

Unfortunately, the development of **OLED** displays is behind that of LCDs. Although the field of Organic Optoelectronics has been an active research field for nearly two decades, the current state of organic transistors (OFETs) is similar to that of transistors in the 1960s. In order to create a fully organic display, OFETs are necessary for such purposes as driving and selecting particular OLEDs. Fabricating OLEDs with low operating voltages and a lifetime suitable for commercial use has been difficult to achieve. It was not until **1987** that the first vacuum-deposited OLEDs with practical

Figure 2-1: Cadence OLED-on-Silicon Display Driver

operating voltages were successfully demonstrated **[8].** However, the voltage-to-light characteristics of OLEDs are still difficult to match from device-to-device, and can degrade significantly over time. This disadvantage severely limits the display functionality and lifetime $(\sim 1000$ hours) [2].

After such a short time, the OLEDs degrade and the display produces nonuniform brightness and contrast. Current solutions address the issue of non-uniformity, but they simply do not address the problem of **OLED** degradation as a function of time, use, and environmental factors. Degradation is one of the main barriers to widespread **OLED** display commercialization. Thus, **OLED** displays have found their way into simple, small applications, but not yet into large-format displays.

2.2.3 Modern OLED Displays

In **2003,** Kodak released the first digital camera with an **OLED** display, and Sanyo jointly developed with Kodak a **15" OLED** display monitor. In addition, some cell phones and watches are already beginning to use **OLED** displays in Japan and Korea. **LG** has a cell phone with an **OLED** display, and Sony has a MP3 player with a similar feature. To combat **OLED** non-uniformity, much effort has been taken to develop uniform OLEDs and a method of driving the OLEDs with predictable or constant currents.

Cadence Design Systems has come up with one particular solution to this problem.

An example circuit demonstrating this solution is shown in Figure 2-1 **[9].** The input of this circuit is a voltage between **0** and 700mV from a standard computer video card which corresponds to a particular red, green, or blue level. This voltage is first converted to a current using an amplifier, **NMOS** device and calibrated resistor *R1.* The range of this current I_{REF} is between 0 and $500\mu A$. I_{REF} is then added to a precise, externally calibrated current source $I_1 = 500 \mu A$. This reduces the settling time in the next stage which is a multiplying current **DAC.** This block uses a digital contrast input to adjust the gain (contrast) of the current input **by** as much as **±50%. A** digital brightness input then sets a current **DAC** to offset the current output **by** as much as $\pm 500\mu A$. A second $500\mu A$ current source is then used to remove the initial added offset. Finally, the current output I_{OUT} is a precise, digitally scaled and offset version of the original input video voltage, and is used to drive a particular red, green, or blue **OLED.**

Chapter 3

Organic Integrated Circuit Design

While this thesis does not explicitly focus on the design of the organic system, it is important to understand how it was designed and its specifications, particularly those aspects relevant to the silicon chip. This chapter describes the design of this organic integrated circuit, which forms the physical display and is controlled and driven **by** the silicon circuitry.

3.1 Organic Architecture and Specifications

The proposed organic integrated circuit is a 64 **by** 64 pixel display. The chip consists of several layers of organic chemicals and metals which together form devices that produce and detect light (OLEDs and OPDs, respectively), as well as modulate electrical signals (OFETs). **A** die photo of an OPD in series with an **OFET** is shown in Figure **3-1.** For a much more detailed description on how these devices are fabricated on the chemical level, consult Yu's thesis **[6].**

The display was designed with a number of considerations in mind. **A** 64 **by** 64 pixel array was chosen for two reasons. Firstly, the number of rows in the display is limited **by** the required refresh rate. The settling time of each row multiplied **by** the number of rows determines how long it takes to refresh the entire display, as discussed in Section 4.4. Secondly, the number of columns in the display are limited **by** the desired complexity of the whole system. Each silicon chip can control sixteen

Figure **3-1:** OPD/OFET Die Photo

Table **3.1:** Proposed Organic Circuit Specifications

Parameter	Value
Wafer Diameter	100mm
Die Size	64 mm x 64 mm
Display Area	$48mm \times 48mm$
Array Dimensions	64 x 64
Pixel Size	$750 \mu m \times 750 \mu m$
Pixel Area	0.563 mm ²

columns; the more columns, the more silicon chips are required. **A** 64 **by** 64 pixel display was a good compromise of each of these factors, and provides a visually appealing demonstration display. Table **3.1** shows other physical parameters of the organic circuit.

3.1.1 A Pixel/Sensor: A Single OLED/OPD

Each pixel in this display actually consists of an **OLED** pixel, an OPD (Organic Photo-Detector) sensor, and four OFETs used to drive and select specific pixels. **A** circuit schematic of a single pixel/sensor is shown in Figure **3-2.** In this circuit, M1 and M4 are used to select the particular pixel using the *RSEL* (row-select) signal. M2

Figure **3-2:** Organic Pixel/Sensor Circuit Model

is used to mitigate charge injection on *RSEL* transitions. M3 is considerably larger than the other three as it is used to drive the **OLED.** The OPD measures the incident light and produces a linearly proportional current I_{OUT} , which in turn is linearly proportional to the current through the OLED (I_{OLED}) .

There are two significant poles that dominate the frequency characteristics of this circuit. The first is at the gate of M3. It is due to the large gate capacitance of M3 (due to its current-driving requirement) in series with the on-resistance of M1. This is modeled to be on the order of $10kHz$ (roughly $1000pF$ in parallel with $10k\Omega$). The second is at the drain of M3. This pole is due to the capacitance of the **OLED** in parallel with its output resistance and the output resistance of M3. This is modeled to be on the order of 100kHz (roughly 100pF in parallel with $10k\Omega$). It is important to remember that these are estimated numbers and depend **highly** on both organic processing technology and the physical display parameters in Table **3.1.**

3.1.2 A Display/Imager: An Array of OLED/OPDs

In order to design a functional display without creating separate drivers and sensors for each individual pixel $(2^{12}$ total for this relatively small display), a column-parallel architecture is used. **A** circuit schematic of an example **3 by 3** pixel display using

Figure **3-3:** Column-Parallel Architecture

such an architecture is shown in Figure **3-3.** In this architecture, one silicon circuit is used to control an entire column of organic pixels. Digital input lines are used to select a particular row. **A** full frame is produced in the following manner:

- **1.** The first row is selected **by** setting the first signal *(RSEL1).* Each of the **¹⁶** *VBRT#* signals are set to an analog value correseponding to a particular pixel brightness.
- 2. Each of the 16 silicon circuits sense I_{OUT} of the OPD and servo V_{DRV} accordingly. This feedback loop is given a fixed amount of time to settle.
- **3.** The second row is selected and the first row is deselected. At this point, the gate capacitances of the drive transistors (M3) must hold the voltages which correspond to the desired pixel brightnesses during the time when this row is not in feedback. The assumption made here is that the leakage current from this capacitor (determined **by** the subthreshold current through M1 and any

Figure 3-4: Discrete Circuit Model

parasitic leakage paths due to inadequate isolation) is small enough to not significantly change the gate voltage of M3 during one refresh cycle.

- 4. Again, each of the **16** silicon circuits sense *IOUT* of the OPD and servo *VDRV* accordingly, this time for row 2.
- **5.** Steps **3** and 4 are repeated for the remaining rows in the display. Once a full frame has been updated, the process repeats again starting with row **1.**

3.2 Discrete Component Model

Since the integrated organic circuit was not available to test at the time of this thesis, a substitute circuit was designed and built using only discrete components. This circuit is shown in Figure 3-4 and was designed with the following characteristics in mind. In general, these characteristics are intended to be equivalent to the organic circuit, with the exception that the input range was reduced to **0-5V** (from 0-20V) to make the implementation easier:

. Input: **0-5V**

Figure **3-5:** Discrete Pixel Model IV Characteristics. The two separate lines in this graph represent the limits of the adjustable attenuator.

- 3 externally adjustable poles $(\sim 10 \text{kHz}, \sim 100 \text{kHz}, \sim 1 \text{MHz})$
- Externally adjustable attenuation factor $({\sim -2 \cdot 10^{-9} \Omega^{-1}})$
- Internal mapping: $0V \rightarrow 10nA$, $5V \rightarrow 0nA$
- Output: 0-10nA, voltage bias: $\sim 2.5V$

This circuit consists of three tunable poles, a PMOS input stage and V-I converter, an adjustable current mirror/attenuator using matched discrete BJTs, and a highimpedance current output stage. The tunable poles are used to model the dynamics of the organic circuit. The PMOS input device **(BSS92)** models the organic p-type **V-**I converter. The MPQ3904 and **MPQ3906** matched **BJT** devices serve to mirror and attenuate the PMOS drain current down to 10nA levels at the output. **A** variable attenuation factor is provided by using a $15M\Omega$ potentiometer. This mirror also provides a high-impedance current output at the *IOUT* node. This output impedance is $\frac{V_A}{I_C}$ (the early voltage divided by the output collector current) which is roughly $\frac{50V}{10nA} = 5G\Omega$. A DC measurement of this circuit is shown in Figure 3-5.

Chapter 4

OLED Optical Feedback Solution

4.1 General Description

This thesis utilizes a technique to improve **OLED** display quality and lifetime. The most general technique uses optical feedback on the pixel level to stabilize the display. It pairs each **OLED** pixel with a light sensor which directly measures the amount of incident light. This measurement can then be used to adjust the circuit driving the **OLED** pixel. Figure 4-1 shows a block diagram of this feedback circuit.

4.2 Prior Optical Feedback Solutions

A number of students at MIT have previously explored using this technique in various ways. Eko Lisuwandi first implemented the optical feedback solution design in his

Figure 4-1: General Optical Feedback Solution

Master's thesis **[3].** His research explored and confirmed the feasibility of an optical feedback solution to stabilize the brightness of an **OLED** display. Lisuwandi built a discrete version of the feedback circuitry for a **5 by 5 OLED** array. An external camera was used as the light sensor for the optical feedback. His results demonstrated that the optical feedback design is a promising solution for **OLED** displays.

Matthew R. Powell continued Lisuwandi's work in designing and revising an integrated version of the circuit [4]. The design was an all-silicon design except for the OLEDs, which were deposited on the chip in a separate organic process. Jennifer **J.** Yu developed the organic-on-silicon process **[6].** The photo-detectors (silicon photodiodes) and the feedback circuits were integrated with the addressing and driver circuits on a single chip. The chip features a **128 by 16** pixel array in a column-parallel architecture **(1** feedback loop per column). This integration of silicon and organic circuits on the same substrate, while unique, posed numerous testing difficulties and limits in size.

4.3 Thesis System Implementation

This thesis goes a step further from the previous work. See Figure 4-2 for a system feedback block diagram. This implementation splits the design into two integrated chips: one silicon and one organic. The integrated organic chip contains an array of OLEDs which together form the display. Each **OLED** is paired with an organic photo-detector (OPD) which measures the incident light. See Chapter **3** for details about this design. The integrated silicon chip contains two primary blocks which together amplify the OPD output, compensate the loop, and drive the **OLED.** See Chapter **5** for details about this implementation.

Figure 4-3 depicts a theoretical system using the silicon and organic components introduced above. Each silicon chip contains **16** channels, each controlling one column in a display. This is referred to as a column-parallel architecture, which is covered in Section **3.1.2.** As discussed later in this chapter, with this particular architecture, the poles of the organic circuit (see Chapter **3)** along with display refresh rate spec-

Figure 4-2: System Block Diagram

Figure 4-3: Integrated Organic **&** Silicon System Block Diagram

Figure 4-4: Feedback System Diagram

ifications limit the number of rows one chip can control to **32** rows. Thus, in this system, each silicon chip can control a **32 by 16** portion of a display. In order to drive a 64 **by** 64 organic display depicted here, **8** silicon chips are required. **A** computer or FPGA-based system controls all of the timing and synchronization signals.

4.4 Feedback/MATLAB Analysis

In order to understand how to design a robust loop compensator, one must fully understand the frequency characteristics of the rest of the system and how they pertain to the loop. Figure 4-4 shows a feedback block diagram for the entire system. As is discussed in Chapter **3,** the most uncertain part of the system is the organic part of this loop. We can simplify this part **by** modeling it as a two-pole system, with poles at estimated values of 10kHz and 100kHz. Derivations of these numbers are described in Chapter **3,** though they are crude estimates and should be expected to vary **by** up to an order of magnitude. Additionally, the gain of the organic circuit, modeled here by K_{OLED} and K_{OPD} will also potentially deviate from expected values.

In order to handle these variations, the silicon circuits must be designed to be as robust as possible. To assist with this, parts of the silicon design use external digital signals to modify its own gain and frequency characteristics over larger ranges. The loop compensator employs a dominant-pole system implemented using a switchcapacitor architecture and is discussed in detail in Chapter **5.** This compensator

Figure 4-5: Feedback System Bode Plot

sets a pole at a default value of 10Hz, much lower than the dynamics of the organic circuit. Additionally, it sets the overall gain of the loop at **100. By** doing this, the compensator will establish a unity-gain frequency of 1kHz for the system, a full decade below the slowest organic pole. This will give the loop more than 84 degrees of phase margin, and will ensure a minimum of 45 degrees if the slowest organic pole should drop a full order of magnitude to 1kHz.

An open-loop bode plot of this stable system is shown in Figure 4-5. This plot shows system poles at 10Hz (silicon dominant-pole), 10kHz **&** 100kHz (organic), and 1MHz (a higher-order op-amp pole). In reality, anything over one-quarter to one-half the switching frequency (a default value of 20kHz) is irrelevant to the overall system dynamics. This plot shows a more than acceptable phase margin, and as a result loop-stability, given the modeled parameters.

The open-loop unity-gain frequency of 1kHz establishes the closed-loop bandwidth

at this same value. This sets the system time-constant at $\tau=1$ ms. Allowing for a minimum of **5** time-constants for the loop to settle means the system must be given 5ms for each row to establish a desired pixel light output. Since in this column-parallel architecture each silicon block controls a whole column of pixels, the desired refresh rate limits the number of rows one silicon chip can control. As an example, in order for the system to have a reasonable refresh rate of **6** frames-per-second (fps), a silicon chip should not control more than **33** rows. Therefore, as mentioned earlier, each silicon chip is limited to controlling **32** rows. Using this architecture, as the display scales and more rows are required, more silicon chips must be used.

It is important to note that this is not a fundamental limit of this particular concept. **A** different architecture could be chosen where there is a single silicon block for every pixel. This would dramatically increase the number of display rows as well as the display refresh rate. However, this quickly becomes impractical due to the large number of signals that would have to be interfaced between the silicon and organic chips. The column parallel architecture reduces the number of signals at the expense of multiple silicon driver chips.

Chapter 5

Silicon Integrated Circuit Design

As mentioned before, the main purpose of the silicon circuits designed for this thesis is to set the desired feedback loop characteristics. Figure **5-1** shows a feedback block diagram of the entire system. This chapter focuses on the design of the upper left quadrant of this system, otherwise labeled as the silicon portion of the display. This will be referred to as the Loop Compensator. Design of the lower left quadrant is discussed in Lin's thesis **[10].** This is referred to as the Current-Sensing Amplifier **(CSA).** Design of the two right quadrants was previously covered in Chapter **3.**

This silicon chip was fabricated using a National Semiconductor **0.35pm 5V** process. Although the minimum feature size is $0.35 \mu m$, in this design L= $0.5 \mu m$ is the smallest length used for switching transistors and $L=1.0\mu m$ for opamp transistors, as

Figure **5-1:** System Block Diagram

Figure **5-2:** Loop Compensator Block Diagram

Metric	Objective
V_{BRT} Input Range (V)	$0 - 5$
V_{SH} Input Range (V)	$0-5$
Input-Referred Offset (V)	< 50 mV
Compensator Gain	100
Percent Error (from a straight line)	$< 1\%$
Compensator Pole Frequency Range (Hz)	5-133
Switch-Capacitor Frequency Range (kHz)	10-40
V_{DRV} Output Range (V)	$0-5$
Capacitive Output Load (pF)	10

Table **5.1:** Loop Compensator Specifications

recommended **by** National. The chip was designed with three external **DC** voltage sources in mind: $V_{DD} = 5V$, $V_{CM} = 2.5V$, & $V_{SS} = 0V$.

5.1 Silicon Architecture and Specifications

Figure **5-2** depicts the forward path of the above feedback loop, which will be referred to as the loop compensator. The purpose of the loop compensator is to establish the overall dynamics of the loop. These dynamics, if left uncompensated, may be unstable or at the very least unpredictable. Specifically, this block must set the desired open-loop gain and crossover frequency, which together will establish the closed-loop dynamics. Detailed specifications are shown in Table **5.1.** In this table, the percent error value refers to the closed-loop system error between V_{BRT} and V_{SH} . Furthermore, the total number of inversions from input signal V_{BRT} to output signal *VDRV* must be even.

In order to meet the above specifications, the loop compensator is divided into four separable blocks. Each of these blocks are themselves a switch-capacitor circuit surrounding an operational amplifier in a feedback configuration. These four blocks are a summing junction, two identical, inverting gain blocks $(10x \text{ each})$ and an inverting, variable dominant-pole block. Detailed descriptions of each of these blocks, as well as the opamps at their cores, is covered in the following sections.

5.2 Summing Junction Block

The purpose of the summing junction is to obtain the difference of the two input signals V_{SH} and V_{BRT} and produce a single-ended output V_1 . Figure 5-3 shows a circuit diagram of this block. (Note, the convention used in circuit diagrams in this thesis will be as follows. The rails shown powering the opamp depicted with a "T" and inverted "T" are $V_{DD}=5V$ and $V_{SS}=0V$, respectively. The ground signal depicted with a downward-pointing arrow is $V_{CM}=2.5V$, as that is the ground with which signals are referenced to for computational purposes.) Since the output is centered around *VCM= ² .5V,* the block performs the following function:

$$
V_{1}(t) = \begin{cases} 0 & \text{if } V_{SH}(t) - V_{BRT}(t) < -2.5, \\ V_{SH}(t) - V_{BRT}(t) + 2.5 & \text{if } -2.5 \le V_{SH}(t) - V_{BRT}(t) \le 2.5, \\ 5 & \text{if } V_{SH}(t) - V_{BRT}(t) > 2.5. \end{cases}
$$
(5.1)

The switch implementation used in this block varies depending on the range of signals the switch is expected to pass. Complementary pass-gate transistors are used where full rail-to-rail signals are expected. Single **NMOS** transistors are used where a lower range $(0-3.5V)$ is expected). The sizes of all switch transistors are (W/L) $0.9 \mu m/0.5 \mu m$.

The block functions as follows. During the reset phase (phase 2, when clk2 is high and clk1 is low) all four capacitors are zeroed **by** connecting both ends to *VcM.* During the signal phase (phase **1,** when clk1 is high and clk2 is low), the inputs of

Figure **5-3:** Summing Junction Circuit Diagram

the opamp settle to $(V_{SH} - V_{CM})/2 + V_{CM}$. Because of this architecture, the opamp input range need only be [1.25, 3.75]. Since $C_1 = C_2$, the following relationship is true:

$$
V_{BRT} - [(V_{SH} - V_{CM})/2 + V_{CM}] = [(V_{SH} - V_{CM})/2 + V_{CM}] - V_1
$$
 (5.2)

Rearranging terms, we get:

$$
V_1(t) = V_{SH}(t) - V_{BRT}(t) + V_{CM}
$$
\n(5.3)

By further imposing the restriction that the opamp output is limited to within a *VDSAT* of its rails, equation **5.1** is obtained.

5.3 Gain Block

The purpose of the two (identical) gain blocks is to set the proper loop gain of **100.** Figure 5-4 shows the circuit diagram for this block. The design is taken from the "Capacitive-Reset Gain Circuit" in [11]. The capacitive ratio C_1/C_2 sets the gain of the block. Since the opamp is in an inverting configuration, the gain of each block is

Figure 5-4: Gain Block Circuit Diagram

also inverting.

With this architecture, the opamp's input offset voltage is cancelled. Furthermore, capacitors *C3* and *C4* are used to improve the output signal in two different ways. Capacitor *C3* is used to hold the output voltage close to its proper value during the reset phase. Capacitor *C4* is a deglitching capacitor that reduces voltage spikes on clock edges.

To see how these advantages occur, consider the reset phase (phase 2, when clk2 is high and clk1 is low). During this phase, capacitors C_1 and C_2 sample the opamp's input offset voltage $(-v_{off})$ while C_3 holds v_{out} close to the value it held during phase **1.** The size of *03* was chosen such that any leakage currents would not significantly change the output voltage in one-half clock period. During the signal phase (phase **1,** when clk1 is high and clk2 is low), the voltage across C_1 is $V_1 - v_{off}$ and the voltage across C_2 is $V_2 - v_{off}$. The opamp offset voltage v_{off} is therefore cancelled. The charge that passes through C_1 must also pass through C_2 , resulting in the following

Figure **5-5:** Dominant-Pole Block Circuit Diagram

input/output relationship for this block:

$$
V_2(t) = \begin{cases} \sim 0 & \text{if } -10(V_1(t) - 2.5) < -2.5, \\ -10(V_1(t) - 2.5) + 2.5 & \text{if } -2.5 \le -10(V_1(t) - 2.5) \le 2.5, \\ \sim 5 & \text{if } -10(V_1(t) - 2.5) > 2.5. \end{cases} \tag{5.4}
$$

5.4 Dominant-Pole Compensation Block (Variable Pole Location)

As the name suggests, this block is responsible for establishing a pole at a precise, but externally variable frequency. The actual frequency of the pole is determined **by** both the switch-capacitor clock frequency as well as the digital signals **PCAP1 & PCAP2,** in addition to the capacitor values in the circuit. Figure **5-5** shows a circuit diagram of this block. The gain of this block is determined by the capacitive ratio C_1/C_2 . In this case, the gain is **-1** due to the inverting configuration. The pole location is

pcap2	pcap1	Uр	f_{sw} =20kHz)
		1.5pF	66.7Hz
		4.5pF	22.2Hz
		7.0pF	14.3 Hz
		10.0pF	10.0 Hz

Table **5.2: PCAP** Settings

determined **by** the following formula:

$$
f_p = \frac{1}{2\pi} f_{sw} \frac{C_2}{C_P} \tag{5.5}
$$

where f_{sw} is the switch-capacitor clock frequency and C_P is the selected capacitor in the pca_{rpole} block (see Section 5.4.1). In the standard case for this design, with f_{sw} $=$ 20kHz, and $C_P = 10.0 \text{pF}$, a pole location of $f_p = 10.0 \text{Hz}$ is obtained.

In order to analyze this circuit, it is much simpler to consider the equivalent RC circuit rather than considering charge transfer during each clock phase. In this analysis, C_1 and C_2 become resistors of value $R_1 = \frac{1}{f_{sw}C_1}$ and $R_2 = \frac{1}{f_{sw}C_2}$. The gain of the block is then $-\frac{R_2}{R_1} = -\frac{C_1}{C_2} = -1$ and the pole is located at $f_p = \frac{1}{2\pi R_2 C_P} = \frac{1}{2\pi} f_{sw} \frac{C_2}{C_P}$, as stated above.

5.4.1 Programmable Capacitor Array (PCA)

The purpose of the programmable capacitor array **(PCA)** block as shown in Figure **5-6** is to provide a method to externally tune the location of the pole. This is an important feature of this design. The block uses two external digital signals pcapl **&** pcap2 to connect in parallel three different capacitors in four different combinations. Table **5.2** shows these four selections, the resulting value of *Cp* in each case, and the value of the resulting pole with a switch-capacitor clock frequency of $f_{sw} = 20kHz$.

Combining this digital pole adjustment with f_{sw} , which allows for a continuous adjustment over the range [10kHz, 40kHz], results in an externally selectable pole over a broad range of frequencies: [5Hz, 133Hz].

Figure **5-6:** Programmable-Capacitor-Array **(PCA)** for Adjustable Pole

5.5 Operational Amplifier Design

The operational amplifiers used in each of the previously discussed blocks are standard 2-stage opamps. There are two slightly different versions, one of which is shown in Figure **5-7,** which is designed for a **1pF** load. This opamp is used in the summing junction and gain blocks. The second opamp is identical with the exception of the compensation capacitor $C_C = 10pF$ and "resistor" NFET with $W/L = 5\mu/1\mu$. This opamp is designed for a **10pF** load and is used in the dominant pole block. Detailed specifications for both of these opamps are shown in Table **5.3.**

5.6 Output Multiplexer

The purpose of the output multiplexer (mux) is to allow the user to externally select four different signals to be output. Figure **5-8** shows a circuit diagram of this 4-to-i mux. **A** simple pass-transistor architecture is used. Refer to Table 5.4 for the mux signals and settings. The four mux inputs are V_{DD} (blanking the display), V_{BRT} (sim-

Figure **5-7:** Operational Amplifier **(1pF** load) Circuit Diagram

Table **5.3:** Opamp Specifications

Metric	1pF Opamp	$10pF$ Opamp
DC Small Signal Gain	870	
Output Range (V)	$0-4.95$	$0-4.95$
Unity Gain Frequency (MHz)	1.3	
Phase Margin (degrees)	65	55
Bias Current (μA)	40	40
Power Dissipation (μW)		

Figure 5-8: Output Multiplexer

Table 5.4: Main Channel **MUX** Settings

MUX1	MUX0	Signal	Mode
		V_{DD}	Blank Display
		V_{BRT}	Feedthrough
		V_{DRV}	Feedback Drive
		C H	Imaging

ply passing through the input signal), *VDRV* (the output of the Loop Compensator), and V_{SH} (the output of the CSA).

Chapter 6

Integrated Silicon Chip Results

6.1 Silicon Chip Overview

The integrated silicon chip which demonstrates the.objectives of this thesis was designed using a Cadence design kit customized for National Semiconductor. The specific process is a 0.35um **5V** process which was chosen for a couple of reasons. Firstly, high speed was not necessary for this particular application and neither were low voltages. Therefore a newer submicron process was not used and a 0.35um process was chosen for its stability. Furthermore, a higher voltage rail was desired in order to better interface with the organic circuitry. **A** 20V rail would be ideal, though there were few National processes with this feature. Instead, a **5V** process was chosen with the intent that an external discrete circuit will be used to bridge the silicon drivers and the organic inputs. Eventually, as the organic devices improve and their operational voltages decrease, the external circuit will be removed and the silicon will drive the organics directly.

A die photo of the fabricated chip is shown in Figure **6-1.** The major components of the chip are highlighted in this photo. There are sixteen main channels which are intended to drive an equal number of display columns. The current inputs feed in along the top of the chip. The signals propagate vertically down through the chip through the Current-Sensing Amplifier blocks followed **by** the Loop Compensator blocks. At the bottom of each channel, these signals pass through a bank of output

Figure **6-1:** Silicon Chip (MITOLEDB) Die Photo

multiplexers (muxes). These muxes combine four different signals which can be externally selected. Refer to Table 5.4 for the mux signals and settings. The sixteen outputs of these channels are then split and branch out to the left and right sides of the chip. The clock drivers on the left side of the chip take one external clock as an input and generate four clocks with the appropriate timing for the switch-capacitor circuitry.

A single test channel is located on the bottom part of the chip. The purpose of the test channel is to characterize each of the individual blocks separately. As a result, this test channel differs from a single main channel in a few significant ways. The **CSA** block is identical with a switch-capacitor gain stage. The Loop Compensator block only contains one -10x gain stage as it was deemed unnecessary to have two identical blocks to characterize separately. Furthermore, most of the key intermediate signals connecting each of the individual blocks were pulled out to pads in order to test these blocks separately. Unfortunately, this caused problems while testing the test channel, as these intermediate nodes were not designed to drive such large capacitances. In most cases, the results from the test channel did not match the main channel, and often, blocks in the test channel would not function properly at all.

The most commonly observed incorrect behavior in the test channel involved the block railing one way or another regardless of input voltages. The theory behind this behavior is that there is an unexpected offset in the inital stages of the test channel. This offset could be caused **by** random transistor mismatch or could be due to a larger than expected input noise level. Since both the **CSA** and the Loop Compensator contain blocks with significant gain factors, a small offset upstream leads to a much larger error downstream, typically resulting in one or more railing outputs.

6.2 Test Setup

^Aprinted circuit board (PCB) was designed to interface all of the appropriate signals to the silicon chip for testing purposes. The board provided a way to connect a data acquisition **(DAQ)** card, up to six **BNC** cables, and numerous other power and data signals to the chip. In addition to a personal computer with Labview code which was briefly used, the test setup included a HP **4156C** Semiconductor Parameter Analyzer. The latter was used to create precise current biases for the chip, and additionally to run **DC** sweeps. Finally, a host of function generators and power supplies were connected to create clock waveforms, sine waveforms, and **DC** voltages.

While making it easy to connect a large number of signals to the silicon chip, the PCB actually caused some measurement problems. Due to the large number of signals lines that were routed on the board, the PCB software autoroute feature was used. Unfortunately, this led to a maze of wires traversing across and around the board. Since many of these signals are switching waveforms, this caused a significant amount of noise and variation on important signal lines. As a result, occasionally the PCB was bypassed and signals were connected directly to the back of the package, with mixed results. Future versions of the PCB will be more carefully routed.

6.3 Measurements & Results

As discussed above, there are some inherent problems which are difficult to get around while testing the test channel. The large capacitive loading of internal nodes modified the measured results from what the simulations predicted. Additionally, there was often contention between external and internal circuits both attempting to drive an intermediate internal node.

The main channel, however, did not suffer from these problems. However, it did have its own limitations. In order to test the Loop Compensator as a stand alone block, only one (V_{BRT}) of its two inputs could be driven. In the main channel, the V_{SH} input is directly driven **by** the **CSA** block, and while it can be measured **by** switching the output mux to the appropriate setting, it cannot be driven directly. Thus, the results below were obtained using the following procedure:

1. Set the output mux to the *VSH* setting **(MUX=11).** Measure the **DC** output of the mux for one channel. This is equivalent to the output of the **CSA** block for

that channel. Record this number and use it to calculate input-referred offset later.

- 2. Switch the output mux to the V_{DRV} setting (MUX=10). Drive the V_{BRT} input corresponding to the same channel with the appropriate waveform. This waveform should have its **DC** value centered around the value obtained in step **1** or else the output will rail (due to the gain of the Loop Compensator). Measure and record the output of the mux, which is now equivalent to the output of the **LC** block for that channel.
- **3.** Repeat step 2 for all other relevant measurements for this channel.

The assumption that is made in the above procedure is that the measured V_{SH} value won't change even though it appears that it is not being externally driven. The justification for this assumption is that while it's not explicitly driven externally, the **CSA** block is driving it internally. The **CSA** input is disconnected, corresponding to $I_{IN} = 0$, a valid input signal. While the input-referred offset of the CSA varies among channels and chips and is unknown at this time (and therefore the **CSA** output is unpredictable), it was found to be time invariant. **A** particular **CSA** output of a particular channel of a certain chip remained the same several days later, even if the test setup was modified. This observation was important, as without it, the following measurements could not be made.

Table **6.1** shows the important performance metrics of the Loop Compensator block, and compares the simulated results to the measured results, along with an associated percent error. Pre-layout simulation results are quoted, as the time it took to complete some of the post-layout simulations was impractical. The following sections discuss each of these measurements and explain where any discrepancies occur.

6.3.1 DC Measurements

In order to determine the open-loop **DC** gain, input referred offset, input commonmode range, and output swing, a **DC** sweep was conducted using the HP **4156C**

Metric	Simulated Value	Measured Value	$%$ -Error
Open-Loop DC Gain	99.6	100.18	0.6
Open-Loop Pole (PCAP=11)	10.0 Hz	10.8 Hz	8.0
Open-Loop Pole (PCAP=10)	14.3Hz	$13.5\mathrm{Hz}$	$5.6\,$
Open-Loop Pole (PCAP=01)	22.2Hz	22.8Hz	2.7
Open-Loop Pole (PCAP=00)	66.7Hz	64.8Hz	2.8
Input-Referred Offset	30mV	49mV	N/A
Input Common-Mode Range	$0-5V$	$0-5V$	N/A
Output (V_{DRV}) Swing	$0-5V$	$0.95 - 4.95V$	N/A

Table **6.1:** Loop Compensator Measured and Simulated (Pre-Layout) Results.

Semiconductor Parameter Analyzer. This sweep was conducted around the V_{SH} value for that channel, as described in the step-by-step procedure above. The data from one particular channel is shown in Figure **6-2.**

This data shows an open-loop **DC** gain of **100.18** and an output swing of **[0.95V,** 4.95V]. The gain matches very well to the simulated value. The output swing matches well at the high end but is off **by** almost 1V at the low end. The initial theory behind this anomaly was that there was parasitic contention among the various signals driving the output mux (see Figure **6-3).** However, this did not show up in any simulation. Specifically, in all simulated scenarios, the output of the mux tracked the V_{DRV} input from rail to rail, with neglible error.

Another theory was that this output voltage could be attributed to a non-zero GND signal. During testing, it was observed that the GND (and V_{DD}) rail contained a significant amount of noise at the switching frequency. Due to large current spikes on the clock edges and finite metal trace resistances, there were significant measured voltage spikes on the **GND** rail. Since the banks of dominant pole compensation blocks and output muxes are physically located near the bottom of the chip, and the **GND** pad is located at the top of the chip, there is a significant IR drop across this GND trace (see Figure 6-4). This metal line can be roughly modeled as a 4.25Ω resistor. With an estimated peak current of 200mA, this results in a local **GND** voltage at the main channel output of **0.85V.** However, although this is not ideal behavior, these spikes should only occur on the clock edges and are transient effects.

ł,

Figure **6-2:** Loop Compensator Input/Output Characteristics

Figure **6-3:** Output Multiplexer

Figure 6-4: Silicon Chip Ground Model **[10]**

Therefore, it is unlikely that these spikes caused the observed **DC** error.

The most likely source of this error is due to incorrect clock signals. During testing, it was observed that the 4 outputs of the clock generation blocks (clkl, clk2, clk1bar, and clk2bar) would initally have the desired behavior. This means that clk1 and clk2 would be non-overlapping 20kHz clock signals, while clk1bar and clk2bar would approximately be their inverses. However, after some testing, often one or more of the clock signals would deviate from this expected behavior. Typically this meant that a particular signal would be stuck on one of the rails and would switch no longer. Occasionally, the signal would still switch, but it would no longer swing from rail to rail. Once such a problem occurred, the particular clock signal would stay in this defective mode permanently. The theory is that the testing process caused some sort of irreversible damage to the chip. The only solution was to begin testing a fresh chip.

In order to verify that this problem could cause the observed **DC** error, the following experiment was conducted. The dominant pole block was simulated with the

Figure **6-5:** Dominant Pole Block with Non-Functional clk1 Signal

clk1 signal set to a constant OV. The remaining clock signals operated as designed. Refer to Figure **6-5,** where the clk1 signal and the **NMOS** transistors it drives have been grayed out to show they are constantly off. In this case, the output is limited **by** the range of the PMOS pass transistor, which is approximately **0.8-1.0** on the low end and **5.0** on the high end. Several **DC** points were simulated and the results are plotted in Figure **6-6.** Note the similarity between this simulation and Figure 6-2, particularly the saturation near 0.9V. The gain of this block is **-1** versus +100 of the whole Loop Compensator, which is why the two graphs slope differently.

It is important to note that this deviation from the designed behavior **will** only slightly reduce the functionality of this chip. It will do this **by** reducing the dynamic range of the output of the loop compensator. This means that the maximum **OLED** brightness will be reached when $V_{DRV} = 1$ V, rather than at a slightly brighter point at OV. However, the **OLED** brightness will change the most when *VDRV* is at higher voltages, specifically when $V_{DRV} - V_{DD}$ is close to the threshold of the driving p-type organic device.

Figure 6-6: DC Sweep Simulation of Dominant Pole Block with $clk1 = 0V$

6.3.2 AC Measurements

Determining the frequency response of the Loop Compensator is critical in assessing its functionality and performance. For this measurement, a sine wave signal generator was used to input waveforms at the V_{BRT} input centered around the V_{SH} DC value. In order to take measurements with reasonable precision, the sine wave was first attenuated using a **10:1** resistive divider. It then passed through the Loop Compensator (a maximum theoretical gain of **100)** and measured at the output. The input amplitude and **DC** bias was set such that the circuit was operating in the high-gain linear region shown in Figure **6-2.** Furthermore, the input was set such that the output covered as close to the full dynamic range of the circuit without clipping. The amplitude of input and output sine waves were measured across a wide range of relevant frequencies, and the results plotted in a log-log format. Finally, this procedure was repeated for all four digital **PCAP** settings, to determine the locations of the variable pole. These tests were conducted at a switch-capacitor frequency of 20kHz, and the results are

Figure 6-7: Loop Compensator Frequency Characteristics $f_{sw} = 20kHz$

shown in Figure 6-7.

The results match the simulations well. At each PCAP setting, they show a roll-off consistent with a single-pole behavior. Furthermore, as the programmable feedback capacitor value is decreased, the bandwidth of the circuit increases. By calculating the 3dB points on this graph (rather than extrapolating the unity-gain frequencies, which can lead to inaccurate results), we can determine the exact location of the pole. At simulated pole locations of 10.0, 14.3, 22.2, and 66.7 Hz, the percent error between measured and simulated results is 8.0%, 5.6%, 2.7%, and 2.8%, respectively. Considering that the individual points in the above figure were obtained by measuring sine wave amplitudes off of an analog scope, these are very good numbers. The remaining sub-8.0 percent error can be attributed to inaccuracies in the way the measurements were taken.

6.3.3 Other Measurements

The input-referred offset was calculated **by** comparing the previously measured value *of VSH* with the *VBRT* voltage that drives the output to **2.5V. By** averaging values from **10** different channels, a value of 49mV was measured. This is fairly close to the simulated value of 30mV, and below the 50mV specification. In the closed-loop system, the offset of the LC block corresponds to the error between the V_{BRT} and *VSH* signals. An offset less than 50mV corresponds to an error less than **1%,** which is acceptable for this design.

The input common-mode range was determined **by** looking at data from as many as **10** different channels on **3** separate chips. This is because the input common-mode is determined by the uncontrollable V_{SH} input. Channels were found with a V_{SH} varying from OV to **5V,** and **DC** sweeps were conducted to verify functionality at these common-mode input voltages. The reason the input of the **LC** (which is the summing junction block) has such a wide common-mode range is that the architecture in this block keeps the op-amp inputs close to V_{CM} , while the actual inputs can vary over a broader range.

Chapter 7

Conclusions

This thesis and associated research presents a novel feedback approach to a practical problem. This problem is one of producing an **OLED** display with improved uniformity and a longer lifetime. First, the organic system was described and modeled. Then. the feedback approach was presented at a higher abstraction level. Next, a silicon system was specified, designed, fabricated and characterized. The results were presented and shown in most cases to match the simulated predictions well. When discrepancies existed, reasoning and simulations were provided regarding their source(s).

Logically, the next step would be to combine the silicon and organic systems and demonstrate functionality of an improved display using this closed-loop feedback technique. However, there are currently a few obstacles to completing this. Primarily, the organic display is simply not ready at the time of the completion of this thesis. The integrated organic fabrication process combining OLEDs, OPDs, and OFETs together in a usable circuit is still being developed, characterized, and improved. Once this organic display is ready, the feedback loop will be a step closer to being complete.

The second difficulty involves the Current-Sensing Amplifier **(CSA).** Much like the Loop Compensator, the **CSA** is composed of several distinct circuit blocks. While each of these blocks functions well as designed individually, when put together suffer from input-referred offsets. The nature of the block (amplifying currents on the nA level) make it very susceptible to noise and test setup variations, which was observed constantly throughout testing. **If** a redesign were to occur, perhaps an architectural change would be useful here, in order to minimize this block's susceptibility to noise and offsets.

Furthermore, the key difficulties in characterizing the Loop Compensator and obtaining measurable and repeatable data were due to non-ideal power rails and clock signals. In future versions of this chip, additional effort should be taken to improve these signals. Implementing a ground plane or a full power/ground grid on metal layers **3** and 4 could mitigate these problems greatly. Additionally, care should be taken when designing the clock drivers and routing them to the appropriate signal blocks.

In general, however, the silicon circuits described herein demonstrate the validity of the feedback approach and their application to improving the uniformity and lifetime of **OLED** displays.

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